

WHAT IS CLAIMED IS:

1. An interconnection between a five layer tape and a semiconductor bonding pad site comprising:

a five layer tape comprising:

a first adhesive layer of a first adhesive material;

a first insulating layer comprised of a first insulation material and disposed on top of the first adhesive layer;

a conductive layer of metal disposed on top of the first insulating layer;

a second insulating layer of a second insulation material disposed on top of the conductive layer; and

a second adhesive layer of a second adhesive material disposed on top of the second insulating layer; and

a silicon die having a contact formed by a solder bump, wherein the conductive layer of metal of the five layer tape is accessible for low resistance contact with the solder bump.

2. The interconnection of claim 1, where the first insulating layer and the first adhesive layer have aligned open areas that expose the conductive layer of metal.

3. The interconnection of claim 1, where the second insulating layer and the second adhesive layer have aligned open areas that expose the conductive layer of metal.

4. The interconnection of claim 1, where the five layer tape is pressed upon the solder bump.

5. The interconnection of claim 4, where the first adhesive layer adheres to a surface of the solder die, thereby holding the bump and the conductive layer in good low resistance contact.